


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32C011F6P7	D5YA*443XXXZ	A	3068	13-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	71.95	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	4.4x6.5	20	L bend	
Comment	Package : YA TSSOP 20 BODY 4.4 PITCH 0.65 0087225			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	DSYA*443XXXZ				6000001.0	1000014.4
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.004	mg	supplier	die	Silicon (Si)	7440-21-3		3.920	mg	979021	54483
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	999	56
				supplier	metallization	Copper (Cu)	7440-50-8		0.036	mg	8991	500
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	2997	167
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	2248	125
				supplier	Passivation	Silicon Oxide	7631-86-9		0.023	mg	5744	320
Leadframe (C7025 + NIPdAu)	M-011 Other inorganic materials	34.433	mg	supplier	alloy	Copper (Cu)	7440-50-8		32.410	mg	941248	450458
				supplier	alloy	Nickel (Ni)	7440-02-0		1.073	mg	31162	14913
				supplier	alloy	Silicon (Si)	7440-21-3		0.232	mg	6738	3225
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.054	mg	1568	751
				supplier	coating	Nickel (Ni)	7440-02-0		0.647	mg	18790	8992
				supplier	coating	Palladium (Pd)	7440-05-3		0.014	mg	407	195
Glue eoxy (86015-25)	M-011 Other inorganic materials	0.848	mg	supplier	coating	Gold (Au)	7440-57-5		0.003	mg	87	42
				supplier	glue	Silver (Ag)	7440-22-4		0.745	mg	878000	10348
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.042	mg	50000	589
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.042	mg	50000	589
				supplier	glue	Acrylate polymer	87320-05-6		0.017	mg	20000	236
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.001	mg	1000	12
Bonding wire (CuA)	M-011 Other inorganic materials	0.219	mg	supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1000	12
				supplier	bonding wire	Copper (Cu)	7440-50-8		0.217	mg	990000	3013
				supplier	bonding wire	Others	Proprietary		0.002	mg	10000	30
Encapsulation (EME-G700KC)	M-011 Other inorganic materials	32.175	mg	supplier	molding compound	Silica, vitreous	60676-86-0		27.952	mg	868745	388495
				supplier	molding compound	Epoxy Resin	85954-11-6		2.364	mg	73464	32852
				supplier	molding compound	Phenol Resin	26834-02-6		1.576	mg	48976	21902
				supplier	molding compound	Carbon black	1333-86-4		0.158	mg	4898	2190
				supplier	molding compound	Bismuth compound	7440-69-9		0.126	mg	3918	1752
Finishing (NIPdAu)	M-011 Other inorganic materials	0.271	mg	supplier	connection coating	Nickel (Ni)	7440-02-0		0.264	mg	974170	3669
				supplier	connection coating	Palladium (Pd)	7440-05-3		0.006	mg	22140	83
				supplier	connection coating	Gold (Au)	7440-57-5		0.001	mg	3690	14